



Material Content Data Sheet



Sales Product Name	IGD01N120H2			Issued		29. August 2013		
MA#	MA000040540							
Package	PG-TO252-3-11			Weight*		363.17 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.824	0.23	0.23	2270	2270
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		646	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		194	
	non noble metal	copper	7440-50-8	234.187	64.49	64.57	644836	645676
wire	non noble metal	aluminium	7429-90-5	0.091	0.02	0.02	249	249
encapsulation	organic material	carbon black	1333-86-4	1.235	0.34		3401	
	inorganic material	antimonytrioxide	1309-64-4	2.470	0.68		6802	
	plastics	brominated resin	-	2.470	0.68		6802	
	plastics	epoxy resin	-	24.701	6.80		68015	
	inorganic material	silicondioxide	60676-86-0	92.630	25.51	34.01	255057	340077
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10298	10298
solder	noble metal	silver	7440-22-4	0.013	0.00		36	
	non noble metal	tin	7440-31-5	0.010	0.00		29	
	non noble metal	lead	7439-92-1	0.496	0.14	0.14	1365	1430
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com